

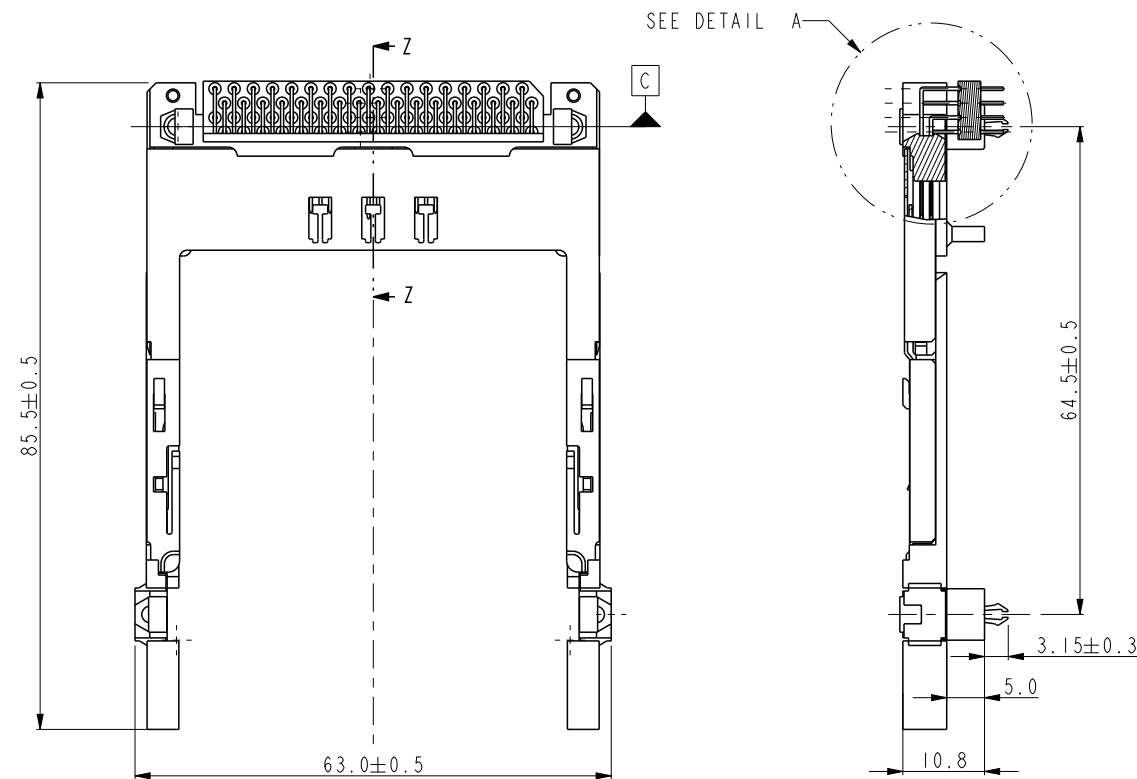
PRODUCT NO.
10118731-050HLF

10118731 - X X X X LF

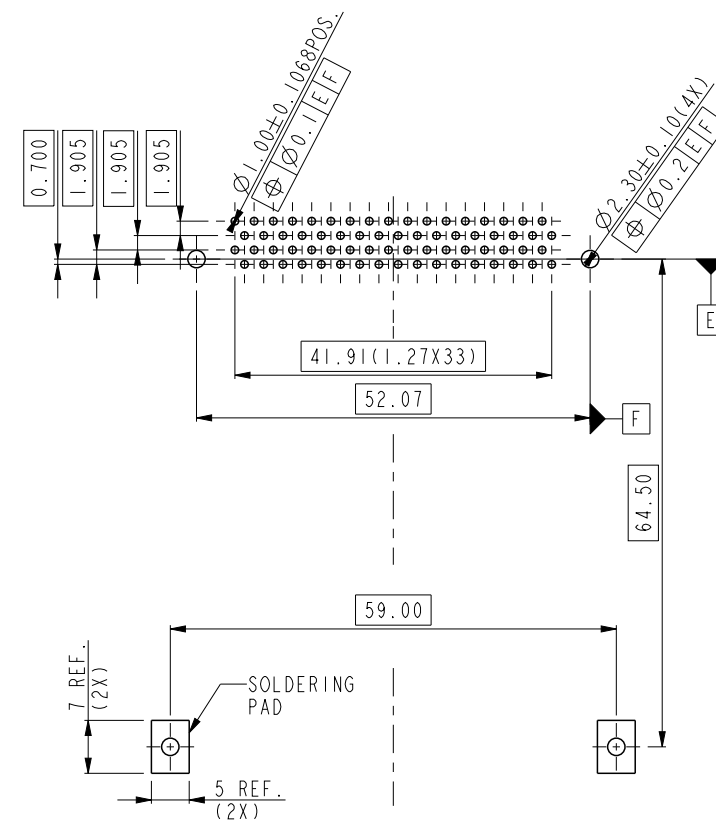
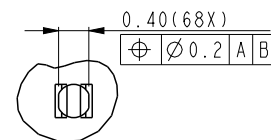
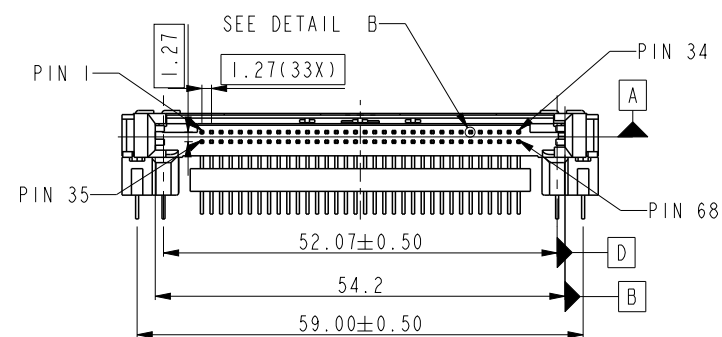
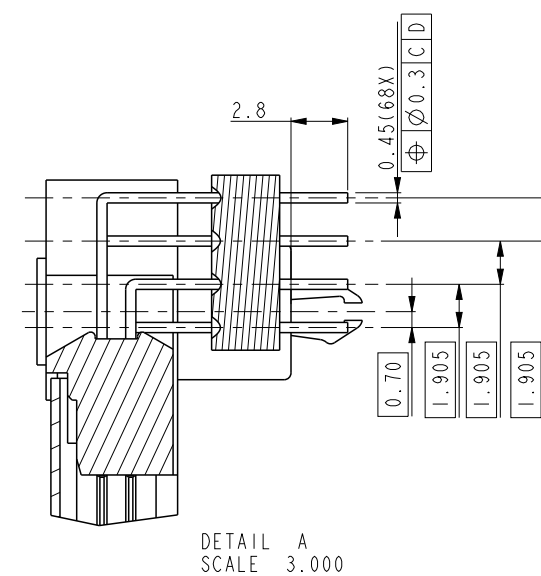
- LEAD FREE
OPTION OF HOLF DOWN
NONE: NO
H: YES
SOLDER TAIL
0: R/A
STAND OFF
0: 0.0MM
5: 5.0MM
MOUNTING STYLE
0: TOP MOUNTING
5: BOTTOM MOUNTING

CONTACT PIN LENGTH		
4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,37	1,17,34,35,51,68

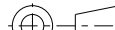
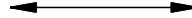
- NOTES:
1. MATERIAL
HOUSING: HALOGEN FREE HIGH TEMPERATURE THERMOPLASTIC
TERMIAL: COPPER ALLOY
COVER: STAINLESS STEEL
2. FINISH(PIN)
a. ALL OVER: UNDER PLATING 1.27um Ni MIN.
b. CONTACT AREA: Au 0.076um MIN.
c. SOLDER AREA: 2.5um MIN. PURE TIN
3. THIS PRODUCT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN WAVE SOLDER APPLICATION WITH 1.0MM MIN.THICK CIRCUIT BOARD.
4. THIS PRODUCT MEETS EUROPEAN UNION DIREACTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
5. PRODUCT SPEC: 110-263.



SECTION Z-Z



RECOMMENDED PCB LAYOUT

spec ref		-		dr		Su-Hua Miao		2012/07/11		projection				MM		size		A3		scale		1.000	
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		Su-Hua Miao		2012/07/16						ecn no		-							
ISO 406																							
ISO 1101																							
ISO 1101		appr		Rick Bian		2012/07/18		product family		-		rel level		Released									
surface		linear		0.X		±0.3				title		68P HF 3.3V NON EJECTOR HEADER ASSEMBLY		dwg no		10118731		rev		A			
ISO 1302																							
ISO 1302																							
angular		0°		±2°		www.fci.com		cat. no.		-		Product - Customer Drw		sheet 1 of 1									